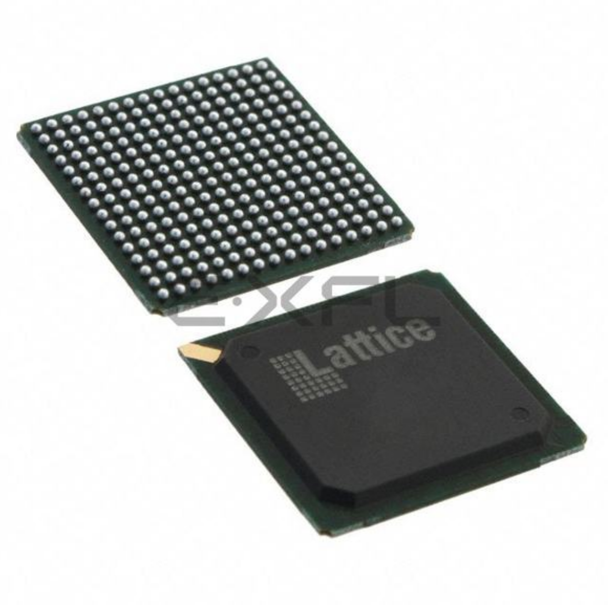

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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications,

Details	
Product Status	Active
Number of LABs/CLBs	2625
Number of Logic Elements/Cells	21000
Total RAM Bits	282624
Number of I/O	193
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	256-BGA
Supplier Device Package	256-FPBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfe2-20e-6fn256c

ROM Mode

ROM mode uses the LUT logic; hence, Slices 0 through 3 can be used in ROM mode. Preloading is accomplished through the programming interface during PFU configuration.

Routing

There are many resources provided in the LatticeECP2/M devices to route signals individually or as buses with related control signals. The routing resources consist of switching circuitry, buffers and metal interconnect (routing) segments.

The inter-PFU connections are made with x1 (spans two PFU), x2 (spans three PFU) and x6 (spans seven PFU). The x1 and x2 connections provide fast and efficient connections in horizontal and vertical directions. The x2 and x6 resources are buffered, allowing the routing of both short and long connections between PFUs.

The LatticeECP2/M family has an enhanced routing architecture that produces a compact design. The Diamond design software takes the output of the synthesis tool and places and routes the design. Generally, the place and route tool is completely automatic, although an interactive routing editor is available to optimize the design.

sysCLOCK Phase Locked Loops (GPLL/SPLL)

The sysCLOCK PLLs provide the ability to synthesize clock frequencies. All the devices in the LatticeECP2/M family support two General Purpose PLLs (GPLLs) which are full-featured PLLs. In addition, some of the larger devices have two to six Standard PLLs (SPLLs) that have a subset of GPLL functionality.

General Purpose PLL (GPLL)

The architecture of the GPLL is shown in Figure 2-5. A description of the GPLL functionality follows.

CLKI is the reference frequency (generated either from the pin or from routing) for the PLL. CLKI feeds into the Input Clock Divider block. The CLKFB is the feedback signal (generated from CLKOP or from a user clock PIN/ logic). This signal feeds into the Feedback Divider. The Feedback Divider is used to multiply the reference frequency.

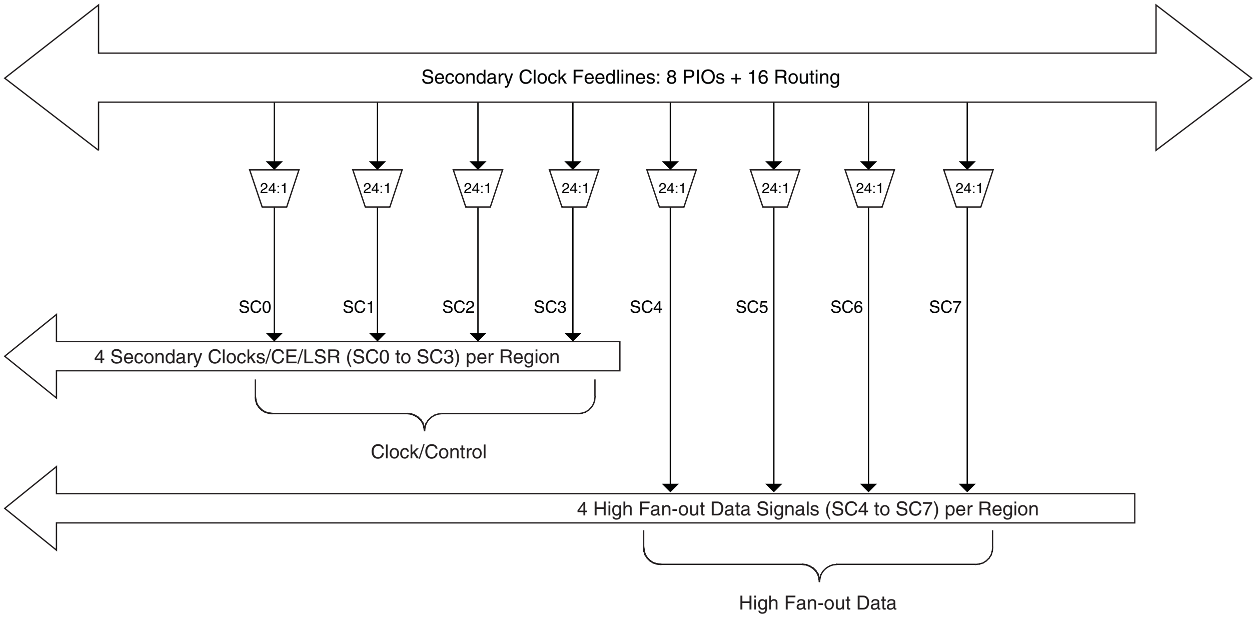
The Delay Adjust Block adjusts either the delays of the reference or feedback signals. The Delay Adjust Block can either be programmed during configuration or can be adjusted dynamically. The setup, hold or clock-to-out times of the device can be improved by programming a delay in the feedback or input path of the PLL, which will advance or delay the output clock with reference to the input clock.

Following the Delay Adjust Block, both the input path and feedback signals enter the Voltage Controlled Oscillator (VCO) block. In this block the difference between the input path and feedback signals is used to control the frequency and phase of the oscillator. A LOCK signal is generated by the VCO to indicate that the VCO has locked onto the input clock signal. In dynamic mode, the PLL may lose lock after a dynamic delay adjustment and not relock until the t_{LOCK} parameter has been satisfied. LatticeECP2/M devices have two dedicated pins on the left and right edges of the device for connecting optional external capacitors to the VCO. This allows the PLLs to operate at a lower frequency. This is a shared resource that can only be used by one PLL (GPLL or SPLL) per side.

The output of the VCO then enters the post-scalar divider. The post-scalar divider allows the VCO to operate at higher frequencies than the clock output (CLKOP), thereby increasing the frequency range. A secondary divider takes the CLKOP signal and uses it to derive lower frequency outputs (CLKOK). The Phase/Duty Select block adjusts the phase and duty cycle of the CLKOP signal and generates the CLKOS signal. The phase/duty cycle setting can be pre-programmed or dynamically adjusted.

The primary output from the post scalar divider CLKOP along with the outputs from the secondary divider (CLKOK) and Phase/Duty select (CLKOS) are fed to the clock distribution network.

Figure 2-16. Secondary Clock Selection

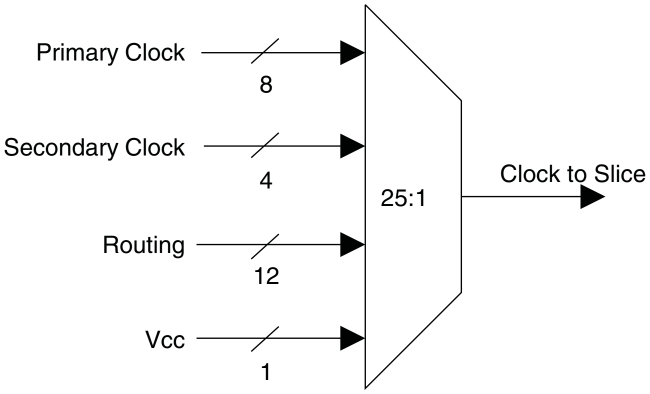


Slice Clock Selection

Figure 2-17 shows the clock selections and Figure 2-18 shows the control selections for Slice0 through Slice2. All the primary clocks and the four secondary clocks are routed to this clock selection mux. Other signals can be used as a clock input to the slices via routing. Slice controls are generated from the secondary clocks or other signals connected via routing.

If none of the signals are selected for both clock and control then the default value of the mux output is 1. Slice 3 does not have any registers; therefore it does not have the clock or control muxes.

Figure 2-17. Slice0 through Slice2 Clock Selection



sysMEM Memory

LatticeECP2/M devices contains a number of sysMEM Embedded Block RAM (EBR). The EBR consists of an 18-Kbit RAM with dedicated input and output registers.

sysMEM Memory Block

The sysMEM block can implement single port, dual port or pseudo dual port memories. Each block can be used in a variety of depths and widths as shown in Table 2-6. FIFOs can be implemented in sysMEM EBR blocks by implementing support logic with PFUs. The EBR block facilitates parity checking by supporting an optional parity bit for each data byte. EBR blocks provide byte-enable support for configurations with18-bit and 36-bit data widths.

Table 2-6. sysMEM Block Configurations

Memory Mode	Configurations
Single Port	16,384 x 1 8,192 x 2 4,096 x 4 2,048 x 9 1,024 x 18 512 x 36
True Dual Port	16,384 x 1 8,192 x 2 4,096 x 4 2,048 x 9 1,024 x 18
Pseudo Dual Port	16,384 x 1 8,192 x 2 4,096 x 4 2,048 x 9 1,024 x 18 512 x 36

Bus Size Matching

All of the multi-port memory modes support different widths on each of the ports. The RAM bits are mapped LSB word 0 to MSB word 0, LSB word 1 to MSB word 1, and so on. Although the word size and number of words for each port varies, this mapping scheme applies to each port.

RAM Initialization and ROM Operation

If desired, the contents of the RAM can be pre-loaded during device configuration. By preloading the RAM block during the chip configuration cycle and disabling the write controls, the sysMEM block can also be utilized as a ROM.

Memory Cascading

Larger and deeper blocks of RAM can be created using EBR sysMEM Blocks. Typically, the Lattice design tools cascade memory transparently, based on specific design inputs.

Single, Dual and Pseudo-Dual Port Modes

In all the sysMEM RAM modes the input data and address for the ports are registered at the input of the memory array. The output data of the memory is optionally registered at the output.

EBR memory supports two forms of write behavior for single port or dual port operation:

1. Normal – Data on the output appears only during a read cycle. During a write cycle, the data (at the current address) does not appear on the output. This mode is supported for all data widths.

IPexpress™

The user can access the sysDSP block via the IPexpress tool, which provides the option to configure each DSP module (or group of modules) or by direct HDL instantiation. In addition, Lattice has partnered with The MathWorks® to support instantiation in the Simulink® tool, a graphical simulation environment. Simulink works with Diamond to dramatically shorten the DSP design cycle in Lattice FPGAs.

Optimized DSP Functions

Lattice provides a library of optimized DSP IP functions. Some of the IP cores planned for the LatticeECP2/M DSP include the Bit Correlator, Fast Fourier Transform, Finite Impulse Response (FIR) Filter, Reed-Solomon Encoder/Decoder, Turbo Encoder/Decoder and Convolutional Encoder/Decoder. Please contact Lattice to obtain the latest list of available DSP IP cores.

Resources Available in the LatticeECP2/M Family

Table 2-9 shows the maximum number of multipliers for each member of the LatticeECP2/M family. Table 2-10 shows the maximum available EBR RAM Blocks in each LatticeECP2/M device. EBR blocks, together with Distributed RAM can be used to store variables locally for fast DSP operations.

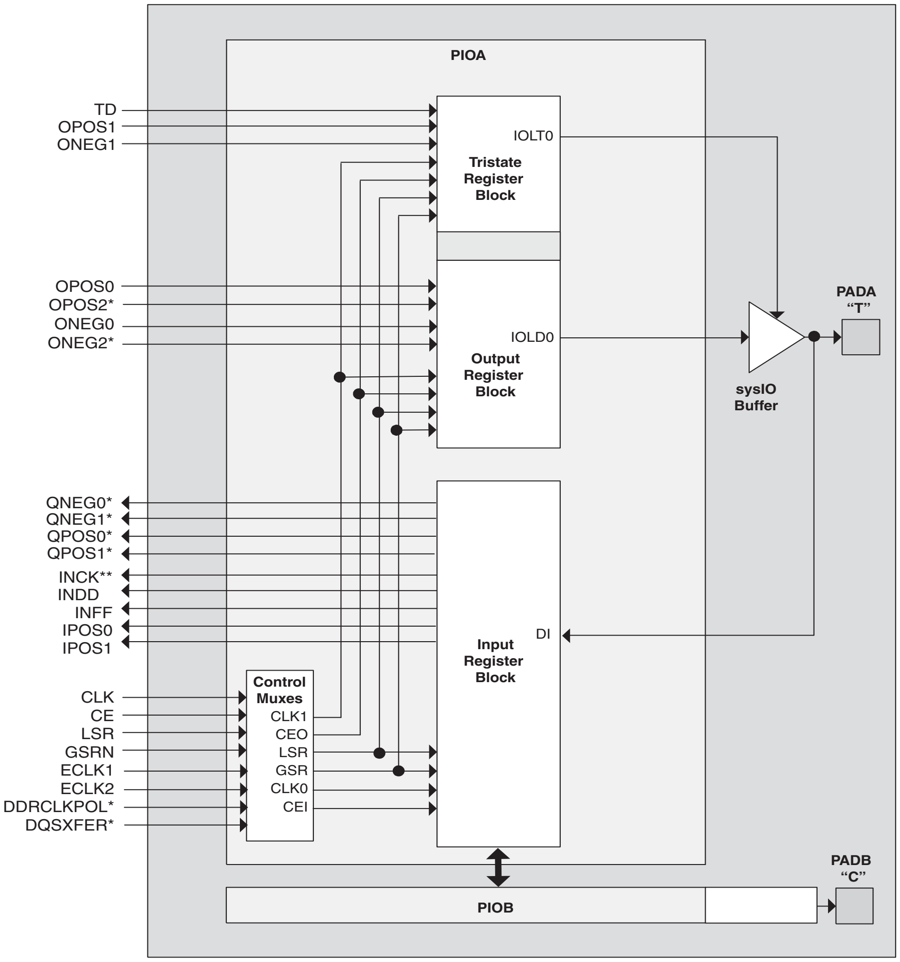
Table 2-9. Maximum Number of DSP Blocks in the LatticeECP2/M Family

Device	DSP Block	9x9 Multiplier	18x18 Multiplier	36x36 Multiplier
ECP2-6	3	24	12	3
ECP2-12	6	48	24	6
ECP2-20	7	56	28	7
ECP2-35	8	64	32	8
ECP2-50	18	144	72	18
ECP2-70	22	176	88	22
ECP2M20	6	48	24	6
ECP2M35	8	64	32	8
ECP2M50	22	176	88	22
ECP2M70	24	192	96	24
ECP2M100	42	336	168	42

Table 2-10. Embedded SRAM in the LatticeECP2/M Family

Device	EBR SRAM Block	Total EBR SRAM (Kbits)
ECP2-6	3	55
ECP2-12	12	221
ECP2-20	15	277
ECP2-35	18	332
ECP2-50	21	387
ECP2-70	60	1106
ECP2M20	66	1217
ECP2M35	114	2101
ECP2M50	225	4147
ECP2M70	246	4534
ECP2M100	288	5308

Figure 2-28. PIC Diagram



*Signals are available on left/right/bottom edges only.
** Selected blocks.

Two adjacent PIOs can be joined to provide a differential I/O pair (labeled as "T" and "C") as shown in Figure 2-28. The PAD Labels "T" and "C" distinguish the two PIOs. Approximately 50% of the PIO pairs on the left and right edges of the device can be configured as true LVDS outputs. All I/O pairs can operate as inputs.

Figure 3-6. SPI4.2 Parameters

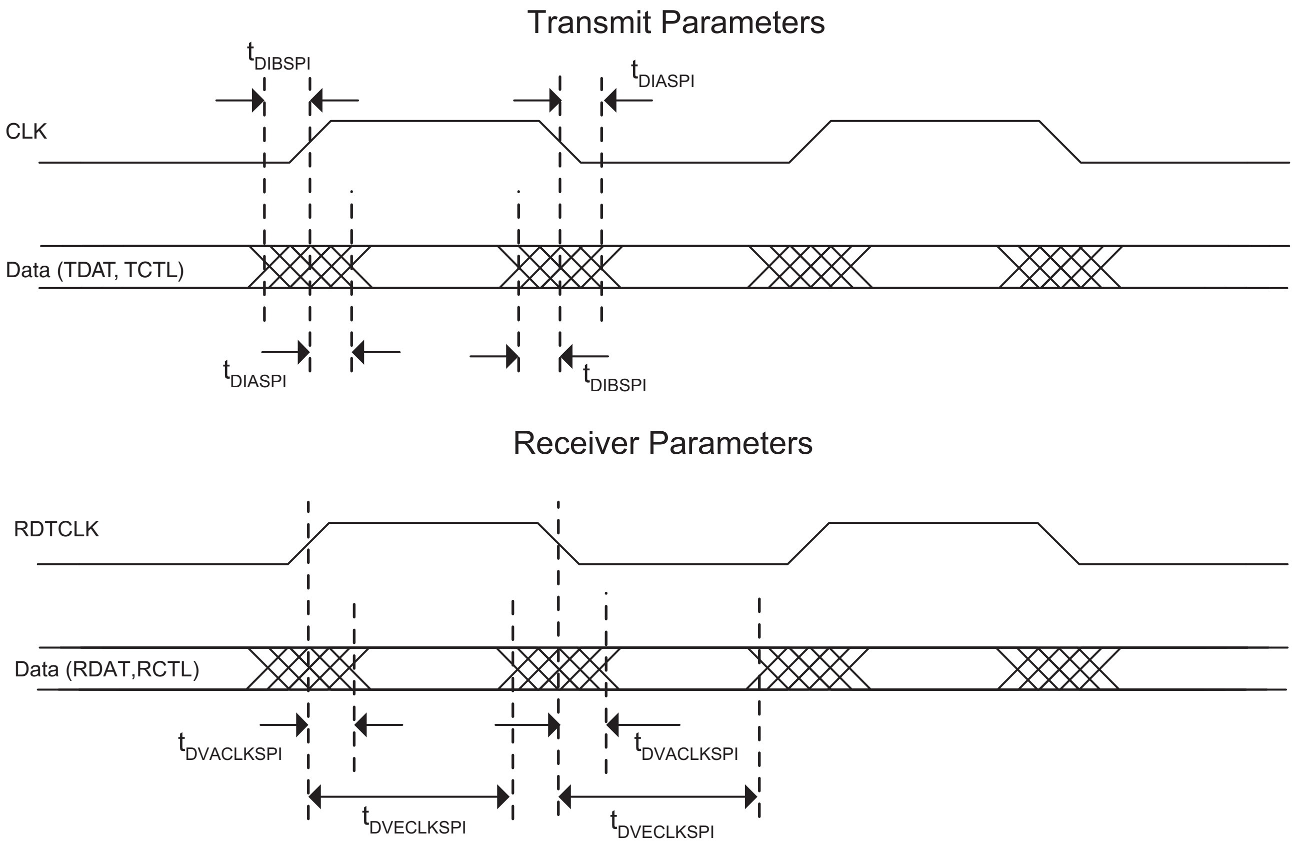
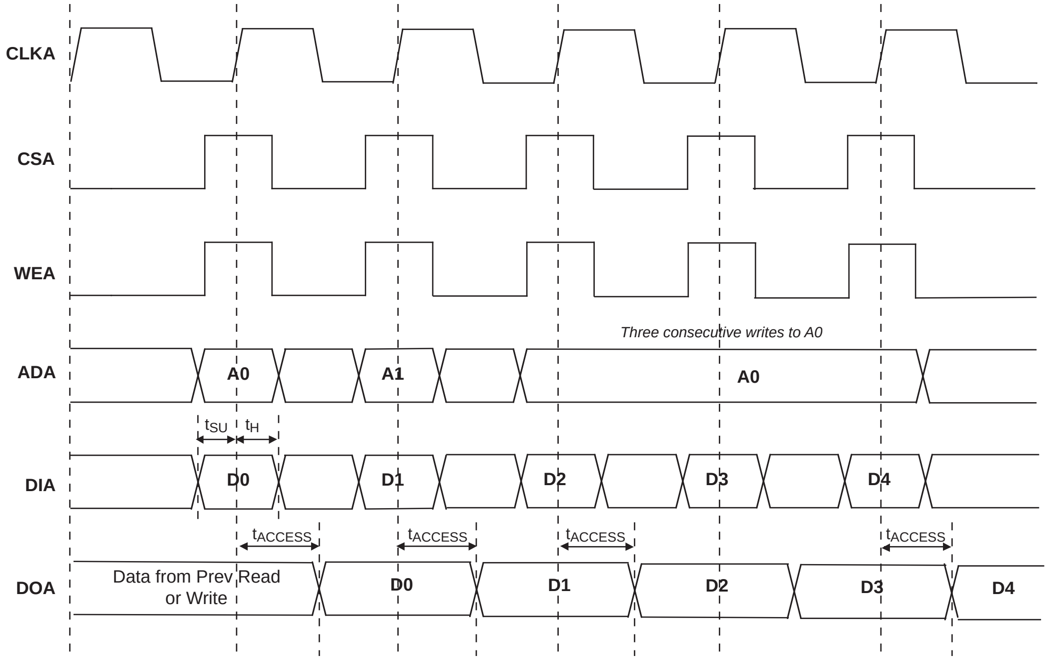


Figure 3-11. Write Through (SP Read/Write on Port A, Input Registers Only)



Note: Input data and address are registered at the positive edge of the clock and output data appears after the positive edge of the clock.

SERDES High-Speed Data Transmitter (LatticeECP2M Family Only)[1, 2]

Table 3-7. Serial Output Timing and Levels

Symbol	Description	Frequency	Min.	Typ.	Max.	Units
$V_{TX-DIFF-P-P-1}$	Differential swing (1V setting)[1, 2]	0.25 to 3.125 Gbps	0.79	0.99	1.19	V, p-p
$V_{TX-DIFF-P-P-1.25}$	Differential swing (1.25V setting)[1, 2]	0.25 to 3.125 Gbps	1.00	1.25	1.50	V, p-p
$V_{TX-DIFF-P-P-1.3}$	Differential swing (1.3V setting)[1, 2]	0.25 to 3.125 Gbps	1.04	1.30	1.56	V, p-p
$V_{TX-DIFF-P-P-1.35}$	Differential swing (1.35V setting)[1, 2]	0.25 to 3.125 Gbps	1.08	1.35	1.62	V, p-p
V_{OCM}	Output common mode voltage	—	V_{CCOB} - 0.75	V_{CCOB} - 0.60	V_{CCOB} - 0.45	V
T_{TX-R}	Rise time (20% to 80%)	—	—	70	—	ps
T_{TX-F}	Fall time (80% to 20%)	—	—	70	—	ps
$Z_{TX-OI-SE}$	Output impedance 50/75/HiZ K Ohms (single-ended)	—	—	50/70 HiZ	—	Ohms
R_{TX-RL}	Return loss (with package)	—	—	9	—	dB

1. All measurements are with 50 ohm impedance.
2. See TN1124, LatticeECP2M SERDES/PCS Usage Guide for actual binary settings.

Table 3-8. Channel Output Jitter - x10 Mode

Description	Frequency	Min.	Typ.	Max.	Units
Deterministic	3.125 Gbps	—	0.08	0.12	UI, p-p
Random	3.125 Gbps	—	0.22	0.38	UI, p-p
Total	3.125 Gbps	—	0.33	0.43	UI, p-p
Deterministic	2.5 Gbps	—	0.08	0.17	UI, p-p
Random	2.5 Gbps	—	0.20	0.25	UI, p-p
Total	2.5 Gbps	—	0.25	0.35	UI, p-p
Deterministic	1.25 Gbps	—	0.03	0.10	UI, p-p
Random	1.25 Gbps	—	0.14	0.19	UI, p-p
Total	1.25 Gbps	—	0.17	0.24	UI, p-p
Deterministic	250 Mbps	—	0.04	0.17	UI, p-p
Random	250 Mbps	—	0.12	0.13	UI, p-p
Total	250 Mbps	—	0.15	0.29	UI, p-p

Note: Values are measured with PRBS 2^7-1, all channels operating, FPGA Logic active, I/Os around SERDES pins quiet, reference clock at x10 mode.

PCI Express Electrical and Timing Characteristics

AC and DC Characteristics

Table 3-16. Transmit[1, 2]

Symbol	Description	Test Conditions	Min	Typ	Max	Units
UI	Unit interval		399.88	400	400.12	ps
$V_{TX-DIFF\_P-P}$	Differential peak-to-peak output voltage		0.8	1.0	1.2	V
$V_{TX-DE-RATIO}$	De-emphasis differential output voltage ratio		0	-3.5	-7.96	dB
$V_{TX-CM-AC\_P}$	RMS AC peak common-mode output voltage		—	20	—	mV
$V_{TX-CM-DC-LINE-DELTA}$	Maximum Common mode voltage delta between n and p channels		—	—	25	mV
$V_{TX-DC-CM}$	Tx DC common mode voltage		0	—	V_{CCOB} + 5%	V
$I_{TX-SHORT}$	Output short circuit current	V_{TX-D+}=0.0V V_{TX-D-}=0.0V	—	—	90	mA
$Z_{TX-DIFF-DC}$	Differential output impedance		80	100	120	Ohms
$T_{TX-RISE}$	Tx output rise time	20 to 80%	0.125	—	—	UI
$T_{TX-FALL}$	Tx output fall time	20 to 80%	0.125	—	—	UI
$L_{TX-SKEW}$	Lane-to-lane static output skew for all lanes in port/link		—	—	1.3	ns
T_{TX-EYE}	Transmitter eye width		0.75	—	—	UI
$T_{TX-EYE-MEDIAN-TO-MAX-JITTER}$[3]			—	—	0.125	UI
C_{TX}	AC coupling capacitor		75	—	200	nF

1. Values are measured at 2.5 Gbps.
2. Compliant to PCI Express v1.1.
3. Measured at 60ps with plug-in board and jitter due to socket removed.

Table 3-17. Receive

Symbol	Description	Test Conditions	Min.	Typ.	Max.	Units
UI	Unit Interval		399.88	400	400.12	ps
$V_{RX-DIFF\_P-P}$	Differential peak-to-peak input voltage		0.175	—	—	V
$V_{RX-IDLE-DET-DIFF\_P-P}$	Idle detect threshold voltage		65	—	175	mV
$Z_{RX-DIFF-DC}$	DC differential input impedance		80	100	120	Ohms
Z_{RX-DC}	DC input impedance		40	50	60	Ohms
$Z_{RX-HIGH-IMP-DC}$[1]	Power-down DC input impedance		200K	—	—	Ohms
T_{RX-EYE}	Receiver eye width		0.4	—	—	UI
$T_{RX-EYE-MEDIAN-TO-MAX-JITTER}$			—	—	0.3	UI

Notes:
1. Measured with external AC-coupling on the receiver
2. Values are measured at 2.5 Gbps

LatticeECP2 Pin Information Summary, LFE2-20 and LFE2-35 (Cont.)

Pin Type		LFE2-20				LFE2-35	
		208 PQFP	256 fpBGA	484 fpBGA	672 fpBGA	484 fpBGA	672 fpBGA
Available DDR-Interfaces per I/O Bank[1]	Bank0	0	0	0	0	0	0
	Bank1	0	0	0	0	0	0
	Bank2	0	1	2	2	2	3
	Bank3	0	0	0	2	0	2
	Bank4	0	2	3	3	3	3
	Bank5	0	1	3	4	3	4
	Bank6	0	1	2	3	1	3
	Bank7	0	1	2	2	2	3
	Bank8	0	0	0	0	0	0
PCI Capable I/Os per Bank	Bank0	0	0	0	0	0	0
	Bank1	0	0	0	0	0	0
	Bank2	0	0	0	0	0	0
	Bank3	0	0	0	0	0	0
	Bank4	19	32	46	50	46	54
	Bank5	18	17	46	68	46	68
	Bank6	0	0	0	0	0	0
	Bank7	0	0	0	0	0	0
	Bank8	0	0	0	0	0	0

1. Minimum requirement to implement a fully functional 8-bit wide DDR bus. Available DDR interface consists of at least 12 I/Os (1 DQS + 1 DQSB + 8 DQs + 1 DM + Bank VREF1).

LFE2-35E/SE and LFE2-50E/SE Logic Signal Connections: 484 fpBGA

LFE2-35E/SE					LFE2-50E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
E4	PL2A	7	VREF2_7/LDQ6	T (LVDS)*	PL2A	7	VREF2_7	T (LVDS)*
E5	PL2B	7	VREF1_7/LDQ6	C (LVDS)*	PL2B	7	VREF1_7	C (LVDS)*
VCCIO	VCCIO7	-			GNDIO7	-		
GNDIO	GNDIO7	-			VCCIO	7		
E3	PL10A	7	LDQ14	T (LVDS)*	PL12A	7	LDQ16	T (LVDS)*
F3	PL10B	7	LDQ14	C (LVDS)*	PL12B	7	LDQ16	C (LVDS)*
F4	PL11A	7	LDQ14	T	PL13A	7	LDQ16	T
F5	PL11B	7	LDQ14	C	PL13B	7	LDQ16	C
E2	PL12A	7	LDQ14	T (LVDS)*	PL14A	7	LDQ16	T (LVDS)*
VCCIO	VCCIO7	7			VCCIO	7		
E1	PL12B	7	LDQ14	C (LVDS)*	PL14B	7	LDQ16	C (LVDS)*
G6	PL13A	7	LDQ14	T	PL15A	7	LDQ16	T
G7	PL13B	7	LDQ14	C	PL15B	7	LDQ16	C
H4	PL14A	7	LDQS14	T (LVDS)*	PL16A	7	LDQS16	T (LVDS)*
GNDIO	GNDIO7	-			GNDIO7	-		
H5	PL14B	7	LDQ14	C (LVDS)*	PL16B	7	LDQ16	C (LVDS)*
F1	PL15A	7	LDQ14	T	PL17A	7	LDQ16	T
F2	PL15B	7	LDQ14	C	PL17B	7	LDQ16	C
VCCIO	VCCIO7	7			VCCIO	7		
G3	PL16A	7	LDQ14	T (LVDS)*	PL18A	7	LDQ16	T (LVDS)*
G4	PL16B	7	LDQ14	C (LVDS)*	PL18B	7	LDQ16	C (LVDS)*
G1	PL17A	7	LDQ14	T	PL19A	7	LDQ16	T
G2	PL17B	7	LDQ14	C	PL19B	7	LDQ16	C
GNDIO	GNDIO7	-			GNDIO7	-		
-	-	-			VCCIO	7		
H6	NC	-			PL25A	7	LUM0_SPLLT_IN_A/LDQ24	T
-	-	-			VCCIO	7		
J6	NC	-			PL25B	7	LUM0_SPLLC_IN_A/LDQ24	C
H3	NC	-			PL26A	7	LUM0_SPLLT_FB_A/LDQ24	T
H2	NC	-			PL26B	7	LUM0_SPLLC_FB_A/LDQ24	C
-	-	-			GNDIO7	-		
-	-	-			VCCIO	7		
H1	PL18A	7	LDQ22		PL37A	7	LDQ41	
J4	PL19A	7	LDQ22	T	PL38A	7	LDQ41	T
J5	PL19B	7	LDQ22	C	PL38B	7	LDQ41	C
VCCIO	VCCIO7	7			VCCIO	7		
J2	PL20A	7	LDQ22	T (LVDS)*	PL39A	7	LDQ41	T (LVDS)*
J1	PL20B	7	LDQ22	C (LVDS)*	PL39B	7	LDQ41	C (LVDS)*
L6	PL21A	7	LDQ22	T	PL40A	7	LDQ41	T
L5	PL21B	7	LDQ22	C	PL40B	7	LDQ41	C
GNDIO	GNDIO7	-			GNDIO7	-		
K3	PL22A	7	LDQS22	T (LVDS)*	PL41A	7	LDQS41	T (LVDS)*
K4	PL22B	7	LDQ22	C (LVDS)*	PL41B	7	LDQ41	C (LVDS)*
K2	PL23A	7	LDQ22	T	PL42A	7	LDQ41	T
VCCIO	VCCIO7	7			VCCIO	7		

LFE2-50E/SE and LFE2-70E/SE Logic Signal Connections: 672 fpBGA (Cont.)

LFE2-50E/SE					LFE2-70E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
AA14	PB38B	5	BDQ42	C	PB47B	5	BDQ51	C
AE10	PB39A	5	BDQ42	T	PB48A	5	BDQ51	T
AF10	PB39B	5	BDQ42	C	PB48B	5	BDQ51	C
W14	PB40A	5	BDQ42	T	PB49A	5	BDQ51	T
AB13	PB40B	5	BDQ42	C	PB49B	5	BDQ51	C
VCCIO	VCCIO5	5			VCCIO5	5		
Y14	PB41A	5	BDQ42	T	PB50A	5	BDQ51	T
AB14	PB41B	5	BDQ42	C	PB50B	5	BDQ51	C
GND	GNDIO5	-			GNDIO5	-		
AE11	PB42A	5	BDQS42	T	PB51A	5	BDQS51	T
AF11	PB42B	5	BDQ42	C	PB51B	5	BDQ51	C
AD14	PB43A	5	BDQ42	T	PB52A	5	BDQ51	T
AA15	PB43B	5	BDQ42	C	PB52B	5	BDQ51	C
AE12	PB44A	5	PCLKT5_0/BDQ42	T	PB53A	5	PCLKT5_0/BDQ51	T
AF12	PB44B	5	PCLKC5_0/BDQ42	C	PB53B	5	PCLKC5_0/BDQ51	C
VCCIO	VCCIO5	5			VCCIO5	5		
GND	GNDIO5	-			GNDIO5	-		
AD15	PB49A	4	PCLKT4_0/BDQ51	T	PB58A	4	PCLKT4_0/BDQ60	T
VCCIO	VCCIO4	4			VCCIO4	4		
AC15	PB49B	4	PCLKC4_0/BDQ51	C	PB58B	4	PCLKC4_0/BDQ60	C
AE13	PB50A	4	BDQ51	T	PB59A	4	BDQ60	T
AF13	PB50B	4	BDQ51	C	PB59B	4	BDQ60	C
AB17	PB51A	4	BDQS51	T	PB60A	4	BDQS60	T
GND	GNDIO4	-			GNDIO4	-		
Y15	PB51B	4	BDQ51	C	PB60B	4	BDQ60	C
AE14	PB52A	4	BDQ51	T	PB61A	4	BDQ60	T
AF14	PB52B	4	BDQ51	C	PB61B	4	BDQ60	C
AA16	PB53A	4	BDQ51	T	PB62A	4	BDQ60	T
VCCIO	VCCIO4	4			VCCIO4	4		
W15	PB53B	4	BDQ51	C	PB62B	4	BDQ60	C
AC17	PB54A	4	BDQ51	T	PB63A	4	BDQ60	T
AB16	PB54B	4	BDQ51	C	PB63B	4	BDQ60	C
AE15	PB55A	4	BDQ51	T	PB64A	4	BDQ60	T
GND	GNDIO4	-			GNDIO4	-		
AF15	PB55B	4	BDQ51	C	PB64B	4	BDQ60	C
AE16	PB56A	4	BDQ60	T	PB65A	4	BDQ69	T
AF16	PB56B	4	BDQ60	C	PB65B	4	BDQ69	C
Y16	PB57A	4	BDQ60	T	PB66A	4	BDQ69	T
AB18	PB57B	4	BDQ60	C	PB66B	4	BDQ69	C
AD17	PB58A	4	BDQ60	T	PB67A	4	BDQ69	T
AD18	PB58B	4	BDQ60	C	PB67B	4	BDQ69	C
VCCIO	VCCIO4	4			VCCIO4	4		
AC18	PB59A	4	BDQ60	T	PB68A	4	BDQ69	T
AD19	PB59B	4	BDQ60	C	PB68B	4	BDQ69	C
GND	GNDIO4	-			GNDIO4	-		
AC19	PB60A	4	BDQS60	T	PB69A	4	BDQS69	T

LFE2-70E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2-70E/SE				
Ball Number	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**
W18	GND	-		
W19	GND	-		
Y14	GND	-		
Y15	GND	-		
Y16	GND	-		
Y17	GND	-		
A2	NC	-		
A3	NC	-		
A4	NC	-		
A5	NC	-		
AB28	NC	-		
AC4	NC	-		
AD23	NC	-		
AE1	NC	-		
AE2	NC	-		
AE29	NC	-		
AE3	NC	-		
AE30	NC	-		
AE4	NC	-		
AE5	NC	-		
AE6	NC	-		
AF1	NC	-		
AF2	NC	-		
AF23	NC	-		
AF26	NC	-		
AF27	NC	-		
AF28	NC	-		
AF29	NC	-		
AF3	NC	-		
AF30	NC	-		
AF4	NC	-		
AF5	NC	-		
AG1	NC	-		
AG13	NC	-		
AG16	NC	-		
AG18	NC	-		
AG2	NC	-		
AG26	NC	-		
AG27	NC	-		
AG28	NC	-		
AG29	NC	-		
AG3	NC	-		
AG30	NC	-		

LFE2M-20E/SE and LFE2M-35E/SE Logic Signal Connections: 256 fpBGA (Cont.)

LFE2M20E/SE					LFE2M35E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
F14	PR24B	2	RDQ22	C (LVDS)*	PR34B	2	RDQ32	C(LVDS)*
F13	PR24A	2	RDQ22	T (LVDS)*	PR34A	2	RDQ32	T (LVDS)*
VCCIO	VCCIO2	2			VCCIO2	2		
GNDIO	GNDIO2	-			GNDIO2	-		
H11	PR14B	2		C	PR14B	2	RDQ15	C
G11	PR14A	2		T	PR14A	2	RDQ15	T
E13	PR13B	2		C (LVDS)*	PR13B	2	RDQ15	C(LVDS)*
F12	PR13A	2		T (LVDS)*	PR13A	2	RDQ15	T (LVDS)*
VCCIO	VCCIO2	2			VCCIO2	2		
F11	PR12B	2	RUM0_SPLLC_FB_A	C	PR12B	2	RUM0_SPLLC_FB_A/RDQ15	C
E12	PR12A	2	RUM0_SPLLT_FB_A	T	PR12A	2	RUM0_SPLLT_FB_A/RDQ15	T
D16	PR11B	2	RUM0_SPLLC_IN_A	C (LVDS)*	PR11B	2	RUM0_SPLLC_IN_A/RDQ15	C(LVDS)*
D15	PR11A	2	RUM0_SPLLT_IN_A	T (LVDS)*	PR11A	2	RUM0_SPLLT_IN_A/RDQ15	T (LVDS)*
C16	PR9B	2	VREF2_2	C	PR9B	2	VREF2_2	C
GNDIO	GNDIO2	-			GNDIO2	-		
B16	PR9A	2	VREF1_2	T	PR9A	2	VREF1_2	T
VCCIO	VCCIO2	2			VCCIO2	2		
F4	XRES	-			XRES	-		
C15	URC_SQ_VCCRX0	12			URC_SQ_VCCRX0	12		
A14	URC_SQ_HDINP0	12		T	URC_SQ_HDINP0	12		T
B15	URC_SQ_VCCIB0	12			URC_SQ_VCCIB0	12		
B14	URC_SQ_HDINN0	12		C	URC_SQ_HDINN0	12		C
C12	URC_SQ_VCCTX0	12			URC_SQ_VCCTX0	12		
A11	URC_SQ_HDOUTP0	12		T	URC_SQ_HDOUTP0	12		T
A12	URC_SQ_VCCOB0	12			URC_SQ_VCCOB0	12		
B11	URC_SQ_HDOUTN0	12		C	URC_SQ_HDOUTN0	12		C
C11	URC_SQ_VCCTX1	12			URC_SQ_VCCTX1	12		
B10	URC_SQ_HDOUTN1	12		C	URC_SQ_HDOUTN1	12		C
C10	URC_SQ_VCCOB1	12			URC_SQ_VCCOB1	12		
A10	URC_SQ_HDOUTP1	12		T	URC_SQ_HDOUTP1	12		T
C14	URC_SQ_VCCRX1	12			URC_SQ_VCCRX1	12		
B13	URC_SQ_HDINN1	12		C	URC_SQ_HDINN1	12		C
C13	URC_SQ_VCCIB1	12			URC_SQ_VCCIB1	12		
A13	URC_SQ_HDINP1	12		T	URC_SQ_HDINP1	12		T
B9	URC_SQ_VCCAUX33	12			URC_SQ_VCCAUX33	12		
D8	URC_SQ_REFCLKN	12		C	URC_SQ_REFCLKN	12		C
D9	URC_SQ_REFCLKP	12		T	URC_SQ_REFCLKP	12		T
C9	URC_SQ_VCCP	12			URC_SQ_VCCP	12		
A5	URC_SQ_HDINP2	12		T	URC_SQ_HDINP2	12		T
C5	URC_SQ_VCCIB2	12			URC_SQ_VCCIB2	12		
B5	URC_SQ_HDINN2	12		C	URC_SQ_HDINN2	12		C
C4	URC_SQ_VCCRX2	12			URC_SQ_VCCRX2	12		
A8	URC_SQ_HDOUTP2	12		T	URC_SQ_HDOUTP2	12		T
C8	URC_SQ_VCCOB2	12			URC_SQ_VCCOB2	12		
B8	URC_SQ_HDOUTN2	12		C	URC_SQ_HDOUTN2	12		C
C7	URC_SQ_VCCTX2	12			URC_SQ_VCCTX2	12		
B7	URC_SQ_HDOUTN3	12		C	URC_SQ_HDOUTN3	12		C
A6	URC_SQ_VCCOB3	12			URC_SQ_VCCOB3	12		

LFE2M20E/SE and LFE2M35E/SE Logic Signal Connections: 484 fpBGA (Cont.)

LFE2M20E/SE					LFE2M35E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
L4	PL24B	7	LDQ22	C (LVDS)*	PL34B	7	LDQ32	C (LVDS)*
M1	PL25A	7	PCLKT7_0/LDQ22	T	PL35A	7	PCLKT7_0/LDQ32	T
GNDIO	GNDIO7	-			GNDIO7	-		
M2	PL25B	7	PCLKC7_0/LDQ22	C	PL35B	7	PCLKC7_0/LDQ32	C
M6	PL27A	6	PCLKT6_0	T (LVDS)*	PL37A	6	PCLKT6_0	T (LVDS)*
M5	PL27B	6	PCLKC6_0	C (LVDS)*	PL37B	6	PCLKC6_0	C (LVDS)*
M3	PL28A	6	VREF2_6	T	PL38A	6	VREF2_6	T
M4	PL28B	6	VREF1_6	C	PL38B	6	VREF1_6	C
VCCIO	VCCIO6	6			VCCIO6	6		
N7	PL31A	6	LLM1_SPLLT_IN_A	T (LVDS)*	PL41A	6	LLM2_SPLLT_IN_A	T (LVDS)*
GNDIO	GNDIO6	-			GNDIO6	-		
N6	PL31B	6	LLM1_SPLLC_IN_A	C (LVDS)*	PL41B	6	LLM2_SPLLC_IN_A	C (LVDS)*
N1	PL32A	6	LLM1_SPLLT_FB_A	T	PL42A	6	LLM2_SPLLT_FB_A	T
N2	PL32B	6	LLM1_SPLLC_FB_A	C	PL42B	6	LLM2_SPLLC_FB_A	C
VCCIO	VCCIO6	6			VCCIO6	6		
GNDIO	GNDIO6	-			GNDIO6	-		
P6	PL38A	6	LDQS38****	T (LVDS)*	PL48A	6	LDQS48****	T (LVDS)*
N5	PL38B	6	LDQ38	C (LVDS)*	PL48B	6	LDQ48	C (LVDS)*
P1	PL39A	6	LDQ38	T	PL49A	6	LDQ48	T
VCCIO	VCCIO6	6			VCCIO6	6		
P2	PL39B	6	LDQ38	C	PL49B	6	LDQ48	C
P3	PL40A	6	LDQ38	T (LVDS)*	PL50A	6	LDQ48	T (LVDS)*
P4	PL40B	6	LDQ38	C (LVDS)*	PL50B	6	LDQ48	C (LVDS)*
P5	PL41A	6	LDQ38	T	PL51A	6	LDQ48	T
GNDIO	GNDIO6	-			GNDIO6	-		
P7	PL41B	6	LDQ38	C	PL51B	6	LDQ48	C
R1	PL42A	6	LLM0_GPLLT_IN_A**	T (LVDS)*	PL57A	6	LLM0_GPLLT_IN_A**/LDQS57****	T (LVDS)*
GNDIO	GNDIO6	-			GNDIO6	-		
R2	PL42B	6	LLM0_GPLLC_IN_A**	C (LVDS)*	PL57B	6	LLM0_GPLLC_IN_A**/LDQ57	C (LVDS)*
R3	PL43A	6	LLM0_GPLLT_FB_A	T	PL58A	6	LLM0_GPLLT_FB_A/LDQ57	T
R4	PL43B	6	LLM0_GPLLC_FB_A	C	PL58B	6	LLM0_GPLLC_FB_A/LDQ57	C
VCCIO	VCCIO6	6			VCCIO6	6		
R6	PL44A	6	LLM0_GDLLT_IN_A**	T (LVDS)*	PL59A	6	LLM0_GDLLT_IN_A**/LDQ57	T (LVDS)*
R5	PL44B	6	LLM0_GDLLC_IN_A**	C (LVDS)*	PL59B	6	LLM0_GDLLC_IN_A**/LDQ57	C (LVDS)*
T1	PL45A	6	LLM0_GDLLT_FB_A	T	PL60A	6	LLM0_GDLLT_FB_A/LDQ57	T
T2	PL45B	6	LLM0_GDLLC_FB_A	C	PL60B	6	LLM0_GDLLC_FB_A/LDQ57	C
GNDIO	GNDIO6	-			GNDIO6	-		
R7	LLM0_PLLCAP	6			LLM0_PLLCAP	6		
T6	PL47A	6	LDQ51	T (LVDS)*	PL62A	6	LDQ66	T (LVDS)*
T7	PL47B	6	LDQ51	C (LVDS)*	PL62B	6	LDQ66	C (LVDS)*
U1	PL48A	6	LDQ51	T	PL63A	6	LDQ66	T
U2	PL48B	6	LDQ51	C	PL63B	6	LDQ66	C
VCCIO	VCCIO6	6			VCCIO6	6		
T3	PL49A	6	LDQ51	T (LVDS)*	PL64A	6	LDQ66	T (LVDS)*
U3	PL49B	6	LDQ51	C (LVDS)*	PL64B	6	LDQ66	C (LVDS)*
U6	PL50A	6	LDQ51	T	NC	-		
U5	PL50B	6	LDQ51	C	PL65B	6	LDQ66	C
GNDIO	GNDIO6	-			GNDIO6	-		

LFE2M35E/SE and LFE2M50E/SE Logic Signal Connections: 672 fpBGA (Cont.)

LFE2M35E/SE					LFE2M50E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
P8	PL45A	6	LDQ48	T	PL49A	6	LDQ52	T
R6	PL45B	6	LDQ48	C	PL49B	6	LDQ52	C
VCCIO	VCCIO6	6			VCCIO6	6		
T1	PL46A	6	LDQ48	T (LVDS)*	PL50A	6	LDQ52	T*
U1	PL46B	6	LDQ48	C (LVDS)*	PL50B	6	LDQ52	C*
R7	PL47A	6	LDQ48	T	PL51A	6	LDQ52	T
T5	PL47B	6	LDQ48	C	PL51B	6	LDQ52	C
GNDIO	GNDIO6	-			GNDIO6	-		
U3	PL48A	6	LDQS48	T (LVDS)*	PL52A	6	LDQS52	T*
U4	PL48B	6	LDQ48	C (LVDS)*	PL52B	6	LDQ52	C*
U5	PL49A	6	LDQ48	T	PL53A	6	LDQ52	T
VCCIO	VCCIO6	6			VCCIO6	6		
U6	PL49B	6	LDQ48	C	PL53B	6	LDQ52	C
U2	PL50A	6	LDQ48	T (LVDS)*	PL54A	6	LDQ52	T*
V1	PL50B	6	LDQ48	C (LVDS)*	PL54B	6	LDQ52	C*
W2	PL51A	6	LDQ48	T	PL55A	6	LDQ52	T
GNDIO	GNDIO6	-			GNDIO6	-		
V2	PL51B	6	LDQ48	C	PL55B	6	LDQ52	C
V4	PL55A	6	LDQ57	T (LVDS)*	PL59A	6		T*
VCCIO	VCCIO6	6			VCCIO6	6		
V3	PL55B	6	LDQ57	C (LVDS)*	PL59B	6		C*
-	-	-			GNDIO6	-		
W4	PL57A	6	LLM0_GPLLT_IN_A**/LDQS57****	T (LVDS)*	PL62A	6	LLM0_GPLLT_IN_A	T*
GNDIO	GNDIO6	-			GNDIO6	-		
W3	PL57B	6	LLM0_GPLLC_IN_A**/LDQ57	C (LVDS)*	PL62B	6	LLM0_GPLLC_IN_A	C*
W1	PL58A	6	LLM0_GPLLT_FB_A/LDQ57	T	PL63A	6	LLM0_GPLLT_FB_A	T
Y1	PL58B	6	LLM0_GPLLC_FB_A/LDQ57	C	PL63B	6	LLM0_GPLLC_FB_A	C
VCCIO	VCCIO6	6			VCCIO6	6		
AA1	PL59A	6	LLM0_GDLLT_IN_A**/LDQ57	T (LVDS)*	PL64A	6	LLM0_GDLLT_IN_A	T*
AB1	PL59B	6	LLM0_GDLLC_IN_A**/LDQ57	C (LVDS)*	PL64B	6	LLM0_GDLLC_IN_A	C*
U7	PL60A	6	LLM0_GDLLT_FB_A/LDQ57	T	PL65A	6	LLM0_GDLLT_FB_A	T
V6	PL60B	6	LLM0_GDLLC_FB_A/LDQ57	C	PL65B	6	LLM0_GDLLC_FB_A	C
GNDIO	GNDIO6	-			GNDIO6	-		
T8	LLM0_PLLCAP	6			LLM0_PLLCAP	6		
W5	PL62A	6	LDQ66	T (LVDS)*	PL67A	6	LDQ71	T*
Y4	PL62B	6	LDQ66	C (LVDS)*	PL67B	6	LDQ71	C*
U8	PL63A	6	LDQ66	T	PL68A	6	LDQ71	T
W6	PL63B	6	LDQ66	C	PL68B	6	LDQ71	C
VCCIO	VCCIO6	6			VCCIO6	6		
Y3	PL64A	6	LDQ66	T (LVDS)*	PL69A	6	LDQ71	T*
AA3	PL64B	6	LDQ66	C (LVDS)*	PL69B	6	LDQ71	C*
V7	NC	-			PL70A	6	LDQ71	T
Y5	PL65B	6	LDQ66	C	PL70B	6	LDQ71	C
GNDIO	GNDIO6	-			GNDIO6	-		
AB2	PL66A	6	LDQS66	T (LVDS)*	PL71A	6	LDQS71	T*
AA4	PL66B	6	LDQ66	C (LVDS)*	PL71B	6	LDQ71	C*
Y6	PL67A	6	LDQ66	T	PL72A	6	LDQ71	T
VCCIO	VCCIO6	6			VCCIO6	6		

LFE2M100E/SE Logic Signal Connections: 900 fpBGA (Cont.)

LFE2M100E/SE				
Ball Number	**Ball/Pad Function**	**Bank**	**Dual Function**	**Differential**
AJ30	LRC_SQ_VCCIB0	13		
AK29	LRC_SQ_HDINP0	13		T
AH30	LRC_SQ_VCCRX0	13		
AG27	CFG2	8		
AD25	CFG1	8		
AG28	CFG0	8		
AG30	PROGRAMN	8		
AG29	CCLK	8		
AC24	INITN	8		
AF27	DONE	8		
GNDIO	GNDIO8	-		
AF28	WRITEN***	8		
AE26	CS1N***	8		
AB23	CSN***	8		
AF29	D0/SPIFASTN***	8		
VCCIO	VCCIO8	8		
AF30	D1***	8		
AD26	D2***	8		
AE29	D3***	8		
GNDIO	GNDIO8	-		
AE30	D4***	8		
AD29	D5***	8		
AC25	D6***	8		
AD30	D7/SPID0***	8		
VCCIO	VCCIO8	8		
AA22	DI/CSSPI0N***	8		
AC26	DOUT/CSON/CSSPI1N***	8		
AA23	BUSY/SISPI***	8		
AB22	RLM0_PLLCAP	3		
AC27	PR102B	3	RLM0_GDLLC_FB_A/RDQ99	C
GNDIO	GNDIO3	-		
AC28	PR102A	3	RLM0_GDLLT_FB_A/RDQ99	T
AC29	PR101B	3	RLM0_GDLLC_IN_A**/RDQ99	C (LVDS)*
AC30	PR101A	3	RLM0_GDLLT_IN_A**/RDQ99	T (LVDS)*
AB30	PR100B	3	RLM0_GPLLC_IN_A**/RDQ99	C
VCCIO	VCCIO3	3		
AA30	PR100A	3	RLM0_GPLLT_IN_A**/RDQ99	T
AB29	PR99B	3	RLM0_GPLLC_FB_A/RDQ99	C (LVDS)*
AB28	PR99A	3	RLM0_GPLLT_FB_A/RDQS99	T (LVDS)*
GNDIO	GNDIO3	-		
Y22	PR98B	3	RDQ99	C
Y23	PR98A	3	RDQ99	T
AB26	PR97B	3	RDQ99	C (LVDS)*

LFE2M70E/SE and LFE2M100E/SE Logic Signal Connections: 1152 fpBGA (Cont.)

	LFE2M70E/SE				LFE2M100E/SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
K11	NC	-			NC	-		
K12	NC	-			NC	-		
K13	NC	-			NC	-		
K23	NC	-			NC	-		
K24	NC	-			NC	-		
K25	NC	-			NC	-		
K26	NC	-			NC	-		
L11	NC	-			NC	-		
L12	NC	-			NC	-		
L13	NC	-			NC	-		
L14	NC	-			NC	-		
L21	NC	-			NC	-		
L22	NC	-			NC	-		
L23	NC	-			NC	-		
L24	NC	-			NC	-		
L25	NC	-			NC	-		
L26	NC	-			NC	-		
M11	NC	-			NC	-		
M24	NC	-			NC	-		
M25	NC	-			NC	-		
M6	NC	-			NC	-		
M8	NC	-			NC	-		
N10	NC	-			NC	-		
N11	NC	-			NC	-		
P10	NC	-			NC	-		
P25	NC	-			NC	-		
P26	NC	-			NC	-		
R9	NC	-			NC	-		
T11	NC	-			NC	-		
U11	NC	-			NC	-		
W11	NC	-			NC	-		
Y10	NC	-			NC	-		
Y11	NC	-			NC	-		
R15	VCCPLL	-			VCCPLL	-		
R20	VCCPLL	-			VCCPLL	-		
Y15	VCCPLL	-			VCCPLL	-		
Y20	VCCPLL	-			VCCPLL	-		

* Supports true LVDS. Other differential signals must be emulated with external resistors.

** These dedicated input pins can be used for GPLLs or GDLLs within the respective quadrant.

*** For density migration, board design must take into account that these sysCONFIG pins are dual function for the lower density devices (ECP2M20 and ECP2M35). They can be either sysCONFIG pins or general purpose I/Os. These pins are dedicated pins for the higher density devices (ECP2M50, ECP2M70, and ECP2M100).

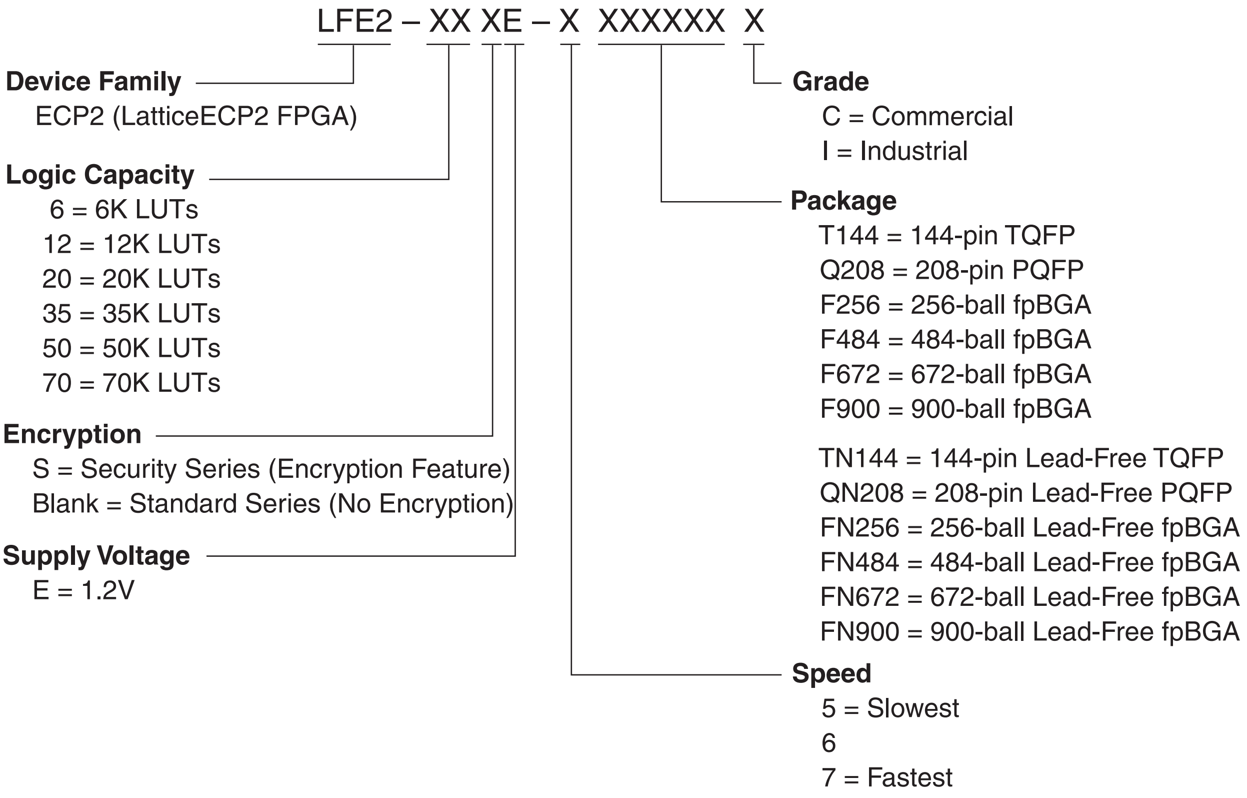
****Due to packaging bond out option, this DQS does not have all the necessary DQ pins bonded out for a full 8-bit data width.

Note: VCCIO and GND pads are used to determine the average DC current drawn by I/Os between GND/VCCIO connections, or between the last GND/VCCIO in an I/O bank and the end of an I/O bank. The substrate pads listed in the Pin Table do not necessarily have a one to one connection with a package ball or pin.

LatticeECP2/M Family Data Sheet
Ordering Information

July 2012 **Data Sheet DS1006**

LatticeECP2 Part Number Description



LFE2 – XX XE – X XXXXXX X

Device Family
ECP2 (LatticeECP2 FPGA)

Logic Capacity
6 = 6K LUTs
12 = 12K LUTs
20 = 20K LUTs
35 = 35K LUTs
50 = 50K LUTs
70 = 70K LUTs

Encryption
S = Security Series (Encryption Feature)
Blank = Standard Series (No Encryption)

Supply Voltage
E = 1.2V

Grade
C = Commercial
I = Industrial

Package
T144 = 144-pin TQFP
Q208 = 208-pin PQFP
F256 = 256-ball fpBGA
F484 = 484-ball fpBGA
F672 = 672-ball fpBGA
F900 = 900-ball fpBGA

TN144 = 144-pin Lead-Free TQFP
QN208 = 208-pin Lead-Free PQFP
FN256 = 256-ball Lead-Free fpBGA
FN484 = 484-ball Lead-Free fpBGA
FN672 = 672-ball Lead-Free fpBGA
FN900 = 900-ball Lead-Free fpBGA

Speed
5 = Slowest
6
7 = Fastest

Ordering Information

Note:þLatticeECP2 devices are dual marked. For example, the commercial speed grade LFE2-50E-7F672C is also marked with industrial grade -6I (LFE2-50E-6F672I). The commercial grade is one speed grade faster than the associated dual mark industrial grade. The slowest commercial speed grade does not have industrial markings. The markings appear as follows:

LatticeECP2/M Family Data Sheet Revision History

September 2013 **Data Sheet DS1006**

Date	Version	Section	Change Summary
February 2006	01.0	—	Initial release.
August 2006	01.1	Introduction	
			Updated Table 1-1 “LatticeECP2 Family Selection Guide”.
		Architecture	Updated Figure 2-2 “PFU Diagram”.
			Updated Figure 2-13 “Secondary Clock Regions ECP2-50”.
			Updated Figure 2-25 “PIC Diagram”.
			Updated Figure 2-26 “Input Register Block for Left, Right and Bottom Edges”.
			Updated Figure 2-28 “Output Register Block for Left, Right and Bottom Edges”.
			Updated Figure 2-30 “DQS Input Routing for Left and Right Edges”.
			Updated Figure 2-32 “Edge Clock, DLL Calibration and DQS Local Bus Distribution”.
			Table 2-15 Selectable Master Clock (CCLK) Frequencies - Removed frequencies 15, 20, 21, 22, 23, 30, 34, 41, 45, 51, 55, 60.
			Replaced “CLKINDEL” with “CLKO”.
			Updated SED section.
			Qualified device migration capability when using DQS banks for DDR interfaces.
		DC and Switching Characteristics	Added VCCPLL to the Recommended Operating Conditions table.
			Removed note 5 from “Hot Specifications” section.
			Added notes 7 and 8 to “Initialization Supply” Current table.
			Change note 6 - “...down to 95MHz” to “...down to 95MHz for DDR and 133MHz for DDR2” .
			New “Typical Building Block Function Performance” numbers.
			New External Switching Characteristics numbers.
			New Internal Switching Characteristics numbers.
			New Family Timing Adders numbers.
			Updated Timings for GPLLs, SPLLs and DLLs.
			Added sysCONFIG waveforms.
			Remove HSTL15D_II from sysIO Recommended Operating Conditions table.
			Updated Supply and Initialization Currents for ECP2-50.
		Pinout Information	Added VCCPLL to the Signal Descriptions table.
			Updated Logic Signal Connections tables to include 484-fpBGA for the ECP2-50.
			Added Logic Signal Connections tables for ECP2-12 devices.
			Updated Pin Information Summary table to include ECP2-12.
			Updated Power Supply and NC Connections table to include ECP2-12.
			Added note 2 to DDR Strobe (DQS) Pin table.
			Added Information on: PCI, DDR & SPI4.2 Capabilities of the device-Package combination.